

CLAIMS

What is claimed is:

- 1 1. A process for personalizing a multi-layer substrate structure comprising:
2 supplying a generic layer having electrical features; and
3 altering said electrical features to produce a personalized layer of said
4 multi-layer substrate.
- 1 2. The process in claim 1, wherein said altering comprises selectively filling
2 vias in said generic layer with conductive material.
- 1 3. The process in claim 1, wherein said altering comprises removing portions
2 of electrical wiring on said generic layer.
- 1 4. The process in claim 1, further comprising supplying a second generic
2 layer identical to said generic layer and altering said electrical features of said
3 second generic layer to produce a second personalized layer different than said
4 personalized layer.
- 1 5. The process in claim 1, wherein said altering changes said generic layer
2 into a plurality of differently personalized layers.

1 6. The process in claim 1, wherein said generic layer includes a grid of vias
2 useful with a plurality of differently personalized layers.

1 7. The process in claim 1, wherein said generic layer includes a pattern of
2 wiring useful with a plurality of differently personalized layers.

1 8. The process in claim 1, wherein said altering comprises selectively filling
2 vias in said generic layer with an insulating material.

1 9. The process in claim 1, wherein said altering comprises selectively forming
2 insulating caps adjacent selected ones of conductive vias in said generic layer to
3 render said selected ones of said conductive vias non-conductive.

1 10. The process in claim 9, wherein said forming of said insulating caps
2 comprises screening a insulating paste.

1 11. The process in claim 9, wherein said forming of said insulating caps
2 comprises placing dry insulating material over said selected ones of said
3 conductive vias.

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1 12. A process for personalizing a multi-layer substrate structure comprising:
2 supplying a layer having generic electrical features; and
3 altering said generic electrical features to produce a personalized layer of
4 said multi-layer substrate.

1 13. The process in claim 12, wherein said altering comprises selectively filling
2 vias in said layer with conductive material.

1 14. The process in claim 12, wherein said altering comprises removing
2 portions of electrical wiring on said layer.

1 15. The process in claim 12, further comprising supplying a second layer
2 identical to said layer and altering said generic electrical features of said second
3 layer to produce a second personalized layer different than said personalized layer.

1 16. The process in claim 12, wherein said altering changes said layer into a
2 plurality of differently personalized layers.

1 17. The process in claim 12, wherein said layer includes a generic grid of vias
2 useful with a plurality of differently personalized layers.

1 18. The process in claim 12, wherein said layer includes a generic pattern of
2 wiring useful with a plurality of differently personalized layers.

Sub 17 1 19. A multi-layer substrate structure comprising:
2 at least one layer having generic electrical features altered to personalize
3 said layer.

1 20. The multi-layer substrate structure in claim 19, wherein said electrical
2 features include vias selectively filled with conductive material.

1 21. The multi-layer substrate structure in claim 19, wherein said electrical
2 features include a wiring pattern having portions selectively removed.

Sub 17 1 22. The multi-layer substrate structure in claim 19, further comprising a
2 second layer similar to said layer and having said generic electrical features
3 altered differently than said layer to personalize said second layer differently than
4 said layer.

1 23. The multi-layer substrate structure in claim 19, wherein said layer is for
2 being changes into a plurality of differently personalized layers.

24. The multi-layer substrate structure in claim 19, wherein said layer includes a generic grid of vias useful with a plurality of differently personalized layers.

25. The multi-layer substrate structure in claim 19, wherein said layer includes a generic pattern of wiring useful with a plurality of differently personalized layers.

26. The multi-layer/substrate structure in claim 19, further comprising:
conductive vias; and
insulating caps adjacent selected ones of said conductive vias, wherein
said insulating caps render said selected ones of said conductive vias non-
conductive.

27. The multi-layer substrate structure in claim 27, wherein said insulating caps comprise a screened insulating paste.

28. The multi-layer substrate structure in claim 27, wherein said insulating caps comprise a dry insulating material.

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